Abstract

Provided is a temperature control method for an inspection system comprising a chuck that holds a substrate having an electronic device to be inspected, and a tester that inspects the electronic device by applying an inspection power to the electronic device, the method comprising: modeling and obtaining a first transfer function of a temperature rise of the electronic device caused by heat generation resulting from applying the inspection power to the electronic device; modeling and obtaining a second transfer function of a temperature of the chuck when a set temperature of the chuck is changed; acquiring an inspection timing of the electronic device from the tester; and starting temperature control of the chuck based on the first transfer function and the second transfer function before an inspection of the electronic device starts.